



特徴 Features

- 塗布形状は自由自在。基板設計の自由度向上 Pattern printing for higher flexibility in board design.
- はんだ粒子による優れた導通信頼性Reliable conductivity by solder particles.
- 仮圧着不要。工程及び装置コストDown Skip Pre-bonding to save process time.

ラインアップ Line-up

ELEPASTE J B series

◆ELEPASTE JB100

particle size:12–15μm min. pitch:200μm
Bonding condition
CURE TEMP. :150°C
CURE TIME :10s
Pressure:1MPa



